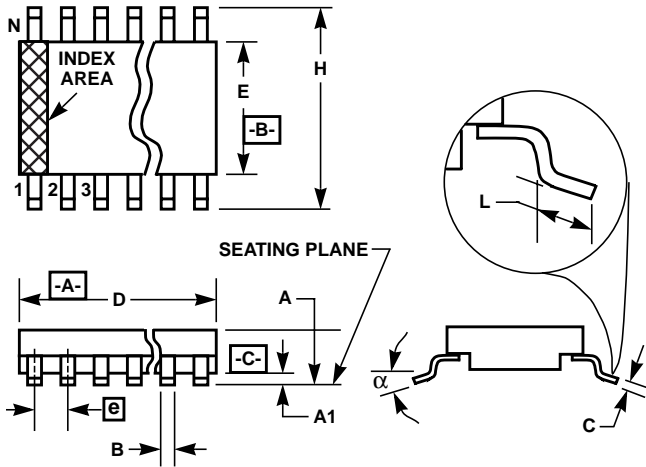


Ceramic SOIC Flatpack Packages (SOIC Flatpack)



**K28.E**  
28 LEAD CERAMIC SOIC FLATPACK PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.092	0.154	2.35	3.90	-
A1	0.004	0.018	0.10	0.45	-
B	0.013	0.020	0.33	0.51	5
C	0.006	0.013	0.15	0.32	-
D	0.697	0.720	17.70	18.30	-
E	0.289	0.301	7.35	7.65	-
e	0.05 BSC		1.27 BSC		-
H	0.393	0.420	10.00	10.65	-
L	0.015	0.050	0.40	1.27	2
N	28		28		3
$\alpha$	0°	8°	0°	8°	-

Rev. 0 4/94

NOTES:

1. Dimensioning and tolerancing per ANSI Y14.5M-1982.
2. "L" is the length of terminal for soldering to a substrate.
3. "N" is the number of terminal positions.
4. Terminal numbers are shown for reference only.
5. The lead width "B", as measured 0.36mm (0.014 inch) or greater above the seating plane, shall not exceed a maximum value of 0.61mm (0.024 inch)
6. Controlling dimension: MILLIMETER.